Allwinner Technology CO., Ltd.

• **History**

Version	Date	Section/ Page	Author	Changes compared to previous issue
v1.0	2017/4/11	All	LX	1. Add support list for H6 v1.0
v1.01	2017/5/19	ALL	WJQ	1. Support KLM8G1GETF-B041, KLMAG1JETD-B041, KLMBG2JETD-B041, KLMCG4JETD-B041, SDINBDG4-8G, SDINBDG4-16G, H26M41208HPR, H26M78208CMR, H26M51002HPR, H26M62002GMR,KLM8G1GETF-B041, KLMAG1JETD-B041, KLMBG2JETD-B041, KLMCG4JETD-B041, SDINBDG4-8G, SDINBDG4-16G, H26M41208HPR, H26M78208CMR, H26M51002HPR, H26M62002GMR KLM8G1GETF-B041, KLMAG1JETD-B041, KLMBG2JETD-B041, KLMCG4JETD-B041, SDINBDG4-8G, SDINBDG4-16G, H26M41208HPR, H26M78208CMR, H26M51002HPR, H26M62002GMR,BTA16GCFHAEET,GD9E8T00GNM-05, FMR16C1D0A-SB, JSMC32BUA2HYAEA, JSMC16AUA2HYAEA,I3E-8GTH7CMRE on H6.
v1.1	2017/7/4	ALL	WJQ	1. Delete H26M51002HPR, H26M62002GMR.

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• Note Introduction

Status	Description
D/S	Datasheet Supported but Need Sample to Full Test
S/T	Sample Full Test Passed and Supported
√	Supported and Mass Production
X	Not Supported
(Blank)	Not Recommended or in Testing

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● **Support List**

Vendor	Capacity (B)	Part Number	eMMC /SD	Cell&Process	Pkg Size (mm)	H6 V1.1
Samsung	8G	KLM8G1WE4A-A001	v4.41		12*16-BGA169	
	16G	KLMAG2WE4A-A001	v4.41		12*16-BGA169	
	4G	KLM4G1FE3B-B001	v4.41		11.5*13-BGA153	
	4G	KLM4G1YEMD-B031	v5.0	TLC/19nm	11.5*13-BGA153	
	8G	KLM8G1WEMB-B031	v5.0	TLC/19nm	11.5*13-BGA153	
	16G	KLMAG2WEMB-B031	v5.0	TLC/19nm	11.5*13-BGA153	
	32G	KLMBG4WEBC-B031	v5.0	TLC/19nm	11.5*13-BGA153	
	16G	KLMAG2GEAC-B031	v5.0	MLC/19nm	11.5*13-BGA153	
	8G	KLM8G1GEAC-B031	v5.0	MLC/19nm	11.5*13-BGA153	
	4G	KLM4G1FEAC-B031	v5.0	MLC/19nm	11*10-BGA153	
	32G	KLMBG4GEAC-B031	v5.0	MLC/19nm	11.5*13-BGA153	
	32G	KLMBG4GE2A-A001	V4.5	MLC	12*16-BGA169	
	16G	KLMAG2GEND-B031	v5.0	MLC/16nm	11.5*13-BGA153	S/T
	32G	KLMBG4GEND-B031	v5.0	MLC/16nm	11.5*13-BGA153	S/T
	8G	KLM8G1WEPD-B031	v5.0	TLC/16nm	11.5*13-BGA153	S/T
	16G	KLMAG2WEPD-B031	v5.0	TLC/16nm	11.5*13-BGA153	S/T
	32G	KLMBG4WEBD-B031	v5.0	TLC/16nm	11.5*13-BGA153	S/T
	64G	KLMCG8GEND-B031	v5.0	MLC/16nm	11.5*13-BGA153	S/T
	8G	KLM8G1GEND-B031	v5.0	MLC/16nm	11.5*13-BGA153	S/T
	64G	KLMCG8WEBD-B031	v5.0	TLC/16nm	11.5*13-BGA153	S/T
	4G	KLM4G1FEPD-B031	v5.0	MLC/16nm	11*10-BGA153	S/T
	8G	KLM8G1GEME-B041	v5.1	MLC/14nm	11.5*13-BGA153	S/T
	16G	KLMAG1JENB-B041	v5.1	MLC/14nm	11.5*13-BGA153	S/T
	32G	KLMBG2JENB-B041	v5.1	MLC/14nm	11.5*13-BGA153	
	64G	KLMCG4JENB-B041	v5.1	MLC/14nm	11.5*13-BGA153	S/T
	8G	KLM8G1GETF-B041	v5.1	MLC/14nm	11.5*13-BGA153	S/T
	16G	KLMAG1JETD-B041	v5.1	MLC/14nm	11.5*13-BGA153	S/T
	32G	KLMBG2JETD-B041	v5.1	MLC/14nm	11.5*13-BGA153	S/T
	64G	KLMCG4JETD-B041	v5.1	MLC/14nm	11.5*13-BGA153	S/T
	8G	SDIN7DP2-8G	v4.5		11.5*13-BGA153	
	16G	SDIN7DU2-16G	v4.41		11.5*13-BGA153	
	4G	SDIN7DP2-4G	v4.5		11.5*13-BGA153	
	8G	SDIN8DE1-8G	v4.5	MLC/19nm	11.5*13-BGA153	
	8G	SDIN8DE2-8G	v4.5	MLC/19nm	11.5*13-BGA153	
	8G	SDIN8DR1-8G	v4.51	TLC/1Ynm	11.5*13-BGA153	S/T

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Vendor	Capacity (B)	Part Number	eMMC /SD	Cell&Process	Pkg Size (mm)	H6
						V1.1
Sandisk	16G	SDIN8DR1-16G	v4.51	TLC/1Ynm	11.5*13-BGA153	S/T
	4G	SDIN8DE2-4G	v4.51	MLC/19nm	11.5*13-BGA153	
	16G	SDIN7DP4-16G	V4.51	MLC	11.5*13-BGA153	
	16G	SDIN8DE4-16G	v4.51	MLC/19nm	11.5*13-BGA153	S/T
	16G	SDIN8DE2-16G	v4.51	MLC/19nm	11.5*13-BGA153	S/T
	32G	SDIN8DE4-32G	v4.51	MLC/19nm	11.5*13-BGA153	S/T
	16G	SDIN9DW4-16G	v5.0	MLC/19nm	11.5*13-BGA153	S/T
	32G	SDIN9DW4-32G	v5.0	MLC/19nm	11.5*13-BGA153	S/T
	32G	SDIN9DS2-32G	v5.0	TLC/1Ynm	11.5*13-BGA153	S/T
	16G	SDIN9DS2-16G	v5.0	TLC/1Ynm	11.5*13-BGA153	S/T
	32G	SDINADF4-32G-L	v5.1	TLC/1Ynm	11.5*13-BGA153	
	8G	SDIN9DS2-8G	v5.0	TLC/1Ynm	11.5*13-BGA153	
	32G	SDINADF4-32G-H	v5.1	TLC/15nm	11.5*13-BGA153	
	16G	SDINADF4-16G-H	v5.1	TLC/15nm	11.5*13-BGA153	
	8G	SDIN8DE1-8G-XI	v4.51	MLC/1xnm	11.5*13-BGA153	
	8G	SDIN8DE2-8G-XA	v4.51	MLC/1xnm	11.5*13-BGA153	
	8G	SDIN8DE1-8G-I	v4.51	MLC/1xnm	11.5*13-BGA153	S/T
	8G	SDIN8DE2-8G-A	v4.51	MLC/1xnm	11.5*13-BGA153	S/T
	8G	SDINBDG4-8G	v5.1	MLC/1znm	11.5*13-BGA153	S/T
	16G	SDINBDG4-16G	v5.1	MLC/1znm	11.5*13-BGA153	S/T
Micron	4G	3EA28-JW878 (MTFC4GLWAM-WT)	v4.5		11.5*13-BGA153	
	8G	3CA28-JW879 (MTFC8GLWAM-WT)	v4.5		11.5*13-BGA153	
	4G	1UA18-JW729 (MTFC4GMTEA-WT)	v4.41		11.5*13-BGA153	
	8G	2GA28-JW686 (MTFC8GLSEA-IT)	v4.41		11.5*13-BGA153	
	8G	3ZA28-JWA48 (MTFC8GACAAEA-WT)	v4.51	MLC	11.5*13-BGA153	
	4G	3ZA28-JWA49 (MTFC4GACAAEA-WT)	v4.51	MLC	11.5*13-BGA153	
	8G	5QA27-JY995 (MTFC8GAKAJCN-1WMT)	v5.0	MLC	11.5*13-BGA153	S/T

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Vendor	Capacity (B)	Part Number	eMMC /SD	Cell&Process	Pkg Size (mm)	H6 V1.1
	4G	6FA27-JY969 (MTFC4GACAJCN-1MWT)	v5.0	MLC	11.5*13-BGA153	S/T
	16G	6FA28-JWB74 (MTFC16GAKAECN-2MWT)	v5.0	MLC	11.5*13-BGA153	S/T
	32G	5SA28-JWB79 (MTFC32GAKAECN-3MWT)	v5.0	MLC	11.5*13-BGA153	S/T
Toshiba	4G	THGBM5G5A1JBAIR	v4.5	MLC/19nm	11.5*13-BGA153	
	8G	THGBM5G6A2JBAIR	v4.5	MLC/19nm	11.5*13-BGA153	
	16G	THGBMAG7A2JBAIR	v4.5	19nm	11.5*13-BGA153	
	4G	THGBMAG5A1JBAIR	v4.5	MLC/19nm	11.5*13-BGA153	
	16G	THGBMBG7D4KBAIR	v5.0	A19nm	11.5*13-BGA153	
	32G	THGBMBG8D4KBAIR	v5.0	MLC/A19nm	11.5*13-BGA153	
	8G	THGBMBG6D1KBAIL	v5.0	MLC/A19nm	11.5*13-BGA153	
	16G	THGBMBG7D2KBAIL	v5.0	MLC/A19nm	11.5*13-BGA153	
	16G	THGBM5G7A2JBAIR	v4.5	MLC/19nm	11.5*13-BGA153	
	16G	THGBMFG7C1LBAIL	v5.0	MLC/15nm	11.5*13-BGA153	S/T
	4G	THGBMBG5D1KBAIL	v5.0	MLC/A19nm	11.5*13-BGA153	S/T
	32G	THGBMFG8C2LBAIL	v5.0	MLC/15nm	11.5*13-BGA153	S/T
	8G	THGBMFG6C1LBAIL	v5.0	MLC/15nm	11.5*13-BGA153	S/T
	4G	THGBMDG5D1LBAIL	v5.1	MLC/15nm	11.5*13-BGA153	S/T
	8G	THGBMHG6C1LBAIL	v5.1	MLC/15nm	11.5*13-BGA153	S/T
	16G	THGBMHG7C1LBAIL	v5.1	MLC/15nm	11.5*13-BGA153	S/T
	32G	THGBMHG8C2LBAIL	v5.1	MLC/15nm	11.5*13-BGA153	S/T
	64G	THGBMHG9C4LBAIL	v5.1	MLC/15nm	11.5*13-BGA153	
SKhynix	4G	H26M31003GMR	v4.51	MLC/20nm	11.5*13-BGA153	
	8G	H26M42003GMR	v4.51	MLC/20nm	11.5*13-BGA153	
	16G	H26M52003EQR	v4.51	MLC/20nm	12*16-BGA169	
	8G	H26M41103HPR	v5.0	MLC/16nm	11.5*13-BGA153	S/T
	16G	H26M52103FMR	v5.0	MLC/16nm	11.5*13-BGA153	S/T
	4G	H26M31001HPR	v4.5	MLC/16nm	11.5*13-BGA153	S/T
	32G	H26M64103EMR	v5.0	MLC/16nm	11.5*13-BGA153	S/T
	8G	H26M41103HPRL	v5.0	MLC/16nm	11.5*13-BGA153	S/T
	8G	H26T43001HPR	v5.0	TLC/16nm	11.5*13-BGA153	S/T
	16G	H26T55001FPR	v5.0	TLC/16nm	11.5*13-BGA153	S/T
	32G	H26T65001EMR	v5.0	TLC/16nm	11.5*13-BGA153	S/T

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Vendor	Capacity (B)	Part Number	eMMC /SD	Cell&Process	Pkg Size (mm)	H6
						V1.1
	16G	H26M52208FPR	v5.1	MLC/16nm	11.5*13-BGA153	S/T
	8G	H26M41204HPR	v5.1	MLC/16nm	11.5*13-BGA153	S/T
	32G	H26M64208EMR	v5.1	MLC/16nm	11.5*13-BGA153	S/T
	8G	H26M41208HPR	v5.1	MLC/16nm	11.5*13-BGA153	S/T
	64G	H26M78208CMR	v5.1	MLC/16nm	11.5*13-BGA153	S/T
Kingston	4G	KE44B26BN	v4.41		12*16-BGA169	
	8G	KE4CV3H5A	v4.41		11.5*13-BGA153	
	16G	KE4CV4H5A	v4.41		11.5*13-BGA153	
	8G	KE4CN3K6A	v4.5		12*16-BGA169	
	4G	KE4CN2H5A	v4.5		11.5*13-BGA153	
	16G	KE4CN4K6A	v4.5		12*16-BGA169	
	16G	EMMC16G-V100	v5.0		11.5*13-BGA153	
	8G	EMMC08G-V100	v5.0		11.5*13-BGA153	
	8G	EMMC08G-M325	v5.1	MLC/15nm	11.5*13-BGA153	S/T
	8G	EMMC08G-T227	v5.0	TLC/15nm	11.5*13-BGA153	S/T
	32G	EMMC32G-T527	v5.0	TLC/15nm	11.5*13-BGA153	S/T
	16G	EMMC16G-T527	v5.0	TLC/15nm	11.5*13-BGA153	S/T
	16G	EMMC16G-M525	v5.1	MLC/15nm	11.5*13-BGA153	S/T
	4G	EMMC04G-M627	v5.1	MLC/15nm	11.5*13-BGA153	
FORESEE	32G	NCEFEH58-32G	V4.51	MLC/16nm	11.5*13.5-	
	8G	NCFSES78-08G	SD 2.0	TLC/21nm	11.5*13.5-	
	16G	NCEFEH58-16G	V4.51	MLC/16nm	11.5*13.5-	
	4G	NCEFES88-04G	v4.51	TLC/21nm	11.5*13.5-	
	8G	NCEFES78-08G	v4.51	TLC/21nm	11.5*13.5-	
	8G	NCFSESA8-08G	SD 2.0	TLC/19nm	11.5*13.5-	
	16G	NCEFBS98-16G	v4.5	TLC/19nm	12*16-BGA169	S/T
	4G	NCEFEM48-04G	v4.5	MLC/20nm	11.5*13.5-	
	16G	NCEMAH59-16G	v5.0	MLC/16nm	11.5*13-BGA153	S/T
	32G	NCEMAH59-32G	v5.0	MLC/16nm	11.5*13-BGA153	S/T
	16G	NCEMBS99-16G	v5.0	TLC/19nm	12*16-BGA169	S/T
	32G	NCEMBS99-32G	v5.0	TLC/19nm	12*16-BGA169	S/T
	8G	NCEFAT28-08G	v4.51	TLC/19nm	11.5*13-BGA153	S/T
	32G	NCEMBSF9-32G	v5.0	TLC/16nm	12*16-BGA169	S/T
	16G	NCEMBSF9-16G	v5.0	TLC/16nm	12*16-BGA169	S/T
	8G	NCEMASD9-08G	v5.0	TLC/16nm	11.5*13-BGA153	S/T
	16G	NCEMBD39-16G	v5.0	MLC/15nm	12*16-BGA169	S/T
	16G	NCEMAD6B-16G	v5.1	TLC/15nm	11.5*13-BGA153	S/T
	8G	NCEMAD7B-08G	v5.0	TLC/15nm	11.5*13-BGA153	S/T

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Vendor	Capacity (B)	Part Number	eMMC /SD	Cell&Process	Pkg Size (mm)	H6
						V1.1
AcSip	8G	NCMMCS08G	v4.5		12*16-BGA169	
	16G	NCMMCS16G	v4.5		12*16-BGA169	
AVEXIR	16G	AVEC016G-FA6	v4.5		11.5*13-BGA153	
EUDAR	8G	EMS1ASCBT1FC008	v4.51		11.5*13-BGA153	
	16G	EMS1ASCBT2FC016	v4.51		11.5*13-BGA153	
Barun	4G	BEM04M5B50XA-	v4.51	MLC/20nm	11.5*13-BGA153	
	4G	BEM04S2B60XA-	v4.51	TLC/19nm	11.5*13-BGA153	
	8G	BEM08S1B60XA-	v4.51	TLC/19nm	11.5*13-BGA153	
	16G	BSB16GCDRS4EM-01	v4.51	TLC/16nm	11.5*13-BGA153	S/T
	8G	BSB08GCDRS4EM-01	v4.51	TLC/16nm	11.5*13-BGA153	
	16G	BTA16GCFHAEET	v5.1	TLC/15nm	11.5*13-BGA153	S/T
Ramaxel	16G	REMKDM316GDBB	v5.0	MLC	11.5*13-BGA153	S/T
	8G	REMKDM308GSBB	v5.0	MLC	11.5*13-BGA153	S/T
	16G	REMSAT416GDBB	v5.0	TLC/A19nm	11.5*13-BGA153	S/T
	8G	REMSAT408GSBB	v5.0	TLC/A19nm	11.5*13-BGA153	S/T
	8G	REMPBT808GSBB	v5.0	TLC/15nm	11.5*13-BGA153	
	16G	REMPBT716GSBB	v5.0	TLC/15nm	11.5*13-BGA153	S/T
Spansion	8G	40410081B1B1W00	v4.51	MLC	11.5*13-BGA153	S/T
	16G	40410161B1B1W01	v4.51	MLC	11.5*13-BGA153	
Gigadevice	8G	GD9E8M00YNI	v5.0	MLC	11.5*13-BGA153	S/T
	4G	GD9E4M00YNI	v5.0	MLC	11.5*13-BGA153	S/T
	8G	GD9E8T00GNM-05	v5.1	TLC/T16nm	11.5*13-BGA153	S/T
FDI	4G	MC1M04M1L3AB	v4.51	MLC	11.5*13-BGA153	
	8G	MC1M08M2L3AB	v4.51	MLC	11.5*13-BGA153	
	16G	MC1M16M4L3AB	v4.51	MLC	11.5*13-BGA153	
SiS	8G	TC008000AA	v5.0	TLC/S16nm	11.5*13-BGA153	S/T
	8G	MC008000AA	v5.0	MLC/H16nm	11.5*13-BGA153	S/T
	16G	MC016000AA	v5.0	MLC/H16nm	11.5*13-BGA153	S/T
	32G	MC032000AA	v5.0	MLC/H16nm	11.5*13-BGA153	S/T
Dosilicon	16G	FMR16C1D0A-SB	v5.0	H3D V2 MLC	11.5*13-BGA153	S/T
JSC	32G	JSMC32BUA2HYAEA	v5.0	H3D V2 MLC	11.5*13-BGA153	S/T
	16G	JSMC16AUA2HYAEA	v5.0	H3D V2 MLC	11.5*13-BGA153	S/T
ESSENCORE	8G	I3E-8GTH7CMRE	v5.0	MLC/T16nm	11.5*13-BGA153	S/T

注1：支持该eMMC需要将各环节MMC驱动更新到最新，并修改sys_config.fex让该eMMC工作在